

REVISIONS			
REV.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	MAR 23/16	J. SI

FS1 - Z38 - X0Z6 - 60

**CONTACT PLATING OPTION**

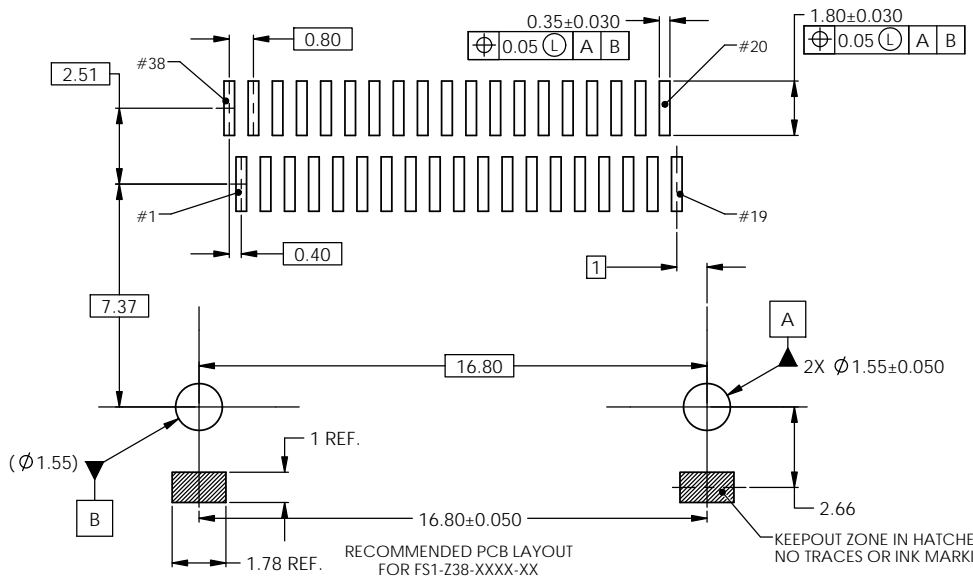
- 2** = 30 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER
- 3** = 15 MICRO INCHES MINIMUM OF GOLD ON MATING END WITH 100 MICRO INCHES MINIMUM OF MATTE TIN ON SOLDER TERMINATION, 50 MIN. MICRO INCHES OF NICKEL UNDER PLATE ALL OVER

**NOTES:**

- 1) MATERIAL:  
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0  
CONTACTS: PHOSPHOR BRONZE  
RESONANCE DAMPENING FEATURE: CONDUCTIVE POLYMER
- 2) ROHS COMPLIANT



DO NOT SCALE DRAWING



THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS	DATE	Amphenol High Speed Interconnects A Division of Amphenol Corp. www.amphenol-highspeed.com	
.X ± 0.2	ANGLES ± 2°	DRAWN A. CHEN	MAR23/16	PART	
XX ± 0.1		DESIGNED A. CHEN	MAR23/16	TITLE	
MATERIAL AND FINISH		CHECKED J. SI	MAR23/16	UltraPort OSFP 4x28	
		DRAWN J. PEN	MAR23/16	38 POSITION CONNECTOR	
DWG. RELEASING		APPROVED ANDY CHEN	MAR23/16	DWG. NO. P-FS1-Z38-X0Z6-60	
CODE IDENT NO. 03554		DWG. APP'D J. SI	MAR23/16	SCALE NTS	PROJECT FS1
				SHEET 1	REV A